

Technical Data Sheet

MODEL NO: S194ANB4-M

 $1.6 \times 0.8 \times 0.4$ mm Blue SMD

Features

●Package: 5000pcs per reel

• Compatible with automatic placement equipment

• Compatible with reflow solder process

Applications:

Indicators

• Automotive: backlighting in dashboard and switch

Backlight for LCD

Dice material	Emitted color	Lens Color	
InGaN	Blue	Water Clear	

Electrical/Optical Characteristics(Ta= 25° C)

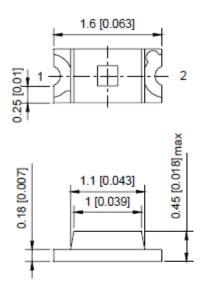
Parameter	Test	Symbol	Value			Unit
Parameter	Condition		Min	Тур	Max	Ullit
Luminous intensity	IF=5mA	lv	28		80	mcd
Dominate Wavelength	IF=5mA	λD	461		476	-
Forward voltage	IF=5mA	VF	2.6		3.4	V
Viewing angle	I _F =5mA	2 0 1/2		120		Deg
Reverse current	V _R =5V	lR			10	μА

Absolute Maximum Ratings(Ta=25°C)

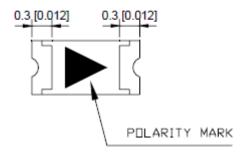
Parameter	Symbol	Value	Unit
Power dissipation	Pd	30	mW
Forward current	lF	10	mA
Reverse voltage	VR	5	V
Operating temperature range	Тор	-40 ~+85	$^{\circ}\!\mathbb{C}$
Storage temperature range	Tstg	-40 ~+85	$^{\circ}\!\mathbb{C}$
Peak pulsing current (1/10 duty f=1kHz)	lfp	20	mA



PACKAGING DIMENSIONS (mm):









VF Rank

D	VF(V)		0 - 177	
Rank	Min	Max	Condition	
F1	2.6	2.7		
F2	2.7	2.8		
G1	2.8	2.9		
G2	2.9	3.0		
H1	3.0	3.1	IF=5mA	
H2	3.1	3.2		
J1	3.2	3.3		
J2	3.3	3.4		

Tolerance:±0.05V

IV Rank

Rank	IV(mcd)		0 177	
	Min	Max	Condition	
Н	28	37		
J	37	48		
K	48	62	IF=5mA	
L	62	80		

Tolerance:±15%

λ D Rank

Rank	λD(
	Min	Max	Condition
3	461	464	
4	464	467	
5	467	470	IF=5mA
6	470	473	
7	473	476	

Tolerance:±1nm

Precautions For Use:

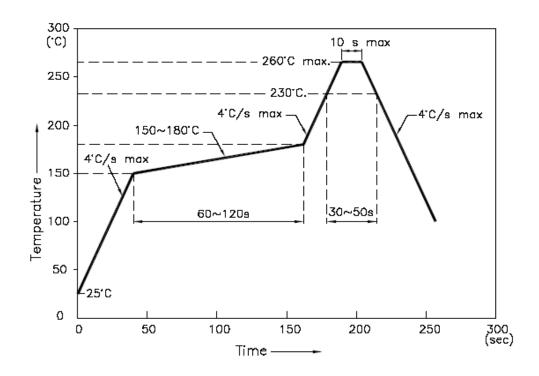
Over - current - proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen)

Storage

- 1. The operation of temperature and R.H. are : 5° C \sim 30 $^{\circ}$ C, 60%R.H. Max.
- 2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a dampproof box with desiccating regent. Considering the tape life, we suggest our customers to use our products within 1.5 year (from production date).
- 3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is : $60^{\circ}\text{C}\pm5^{\circ}\text{C}$ for 15hrs.

■ Reflow Temp/Time





NOTES:

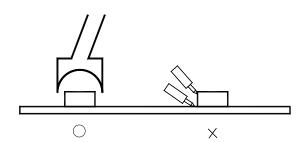
- 1. We recommend the reflow temperature $245\,^{\circ}\text{C}(\pm 5\,^{\circ}\text{C})$.the maximum soldering temperature should be limited to $260\,^{\circ}\text{C}$.
- 2. dont cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

■Soldering iron

Basic spec is \leq 5sec when 260°C. If temperature is higher, time should be shorter (+10°C \rightarrow -1sec). Power dissipation of iron should be smaller than 20W, and temperatures should be controllable. Surface temperature of the device should be under 230°C.

■ Rework

- 1. Customer must finish rework within 5 sec under 260°C.
- 2. The head of iron can not touch copper foil
- 3. Twin-head type is preferred.



■ Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow \ solder etc.